

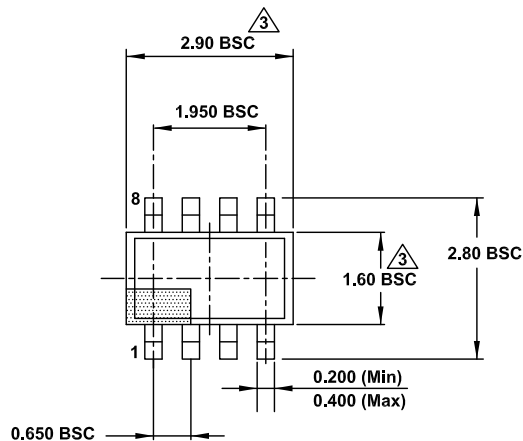
Plastic Packages for Integrated Circuits

Package Outline Drawing

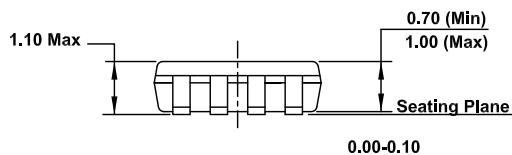
P8.064A

8 Lead Thin Small Outline Transistor Plastic Package (TSOT)

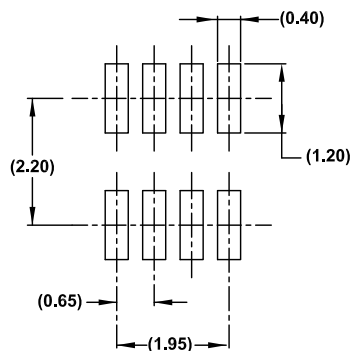
Rev 0, 1/20



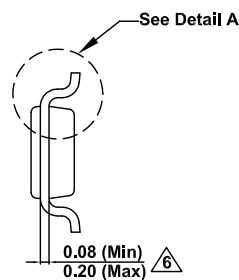
Top View



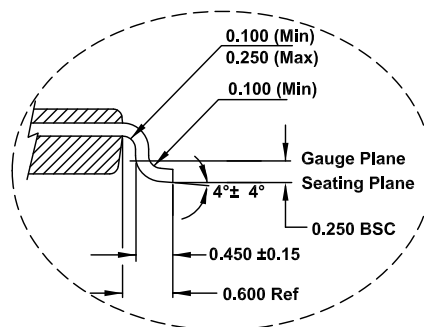
Side View



Typical Recommended Land Pattern



End View



Detail A

Notes:

1. Dimensioning and tolerancing conform to ASME Y14.5m-1994.
2. Die is facing up for mold. Die is facing down for trim/form, that is reverse trim/form.
3. Dimensions are exclusive of mold flash and gate burr.
4. The footlength measuring is based on the gauge plane method.
5. All specifications comply to JEDEC Spec MO193 Issue C.
6. Dimensions are exclusive of solder plating.